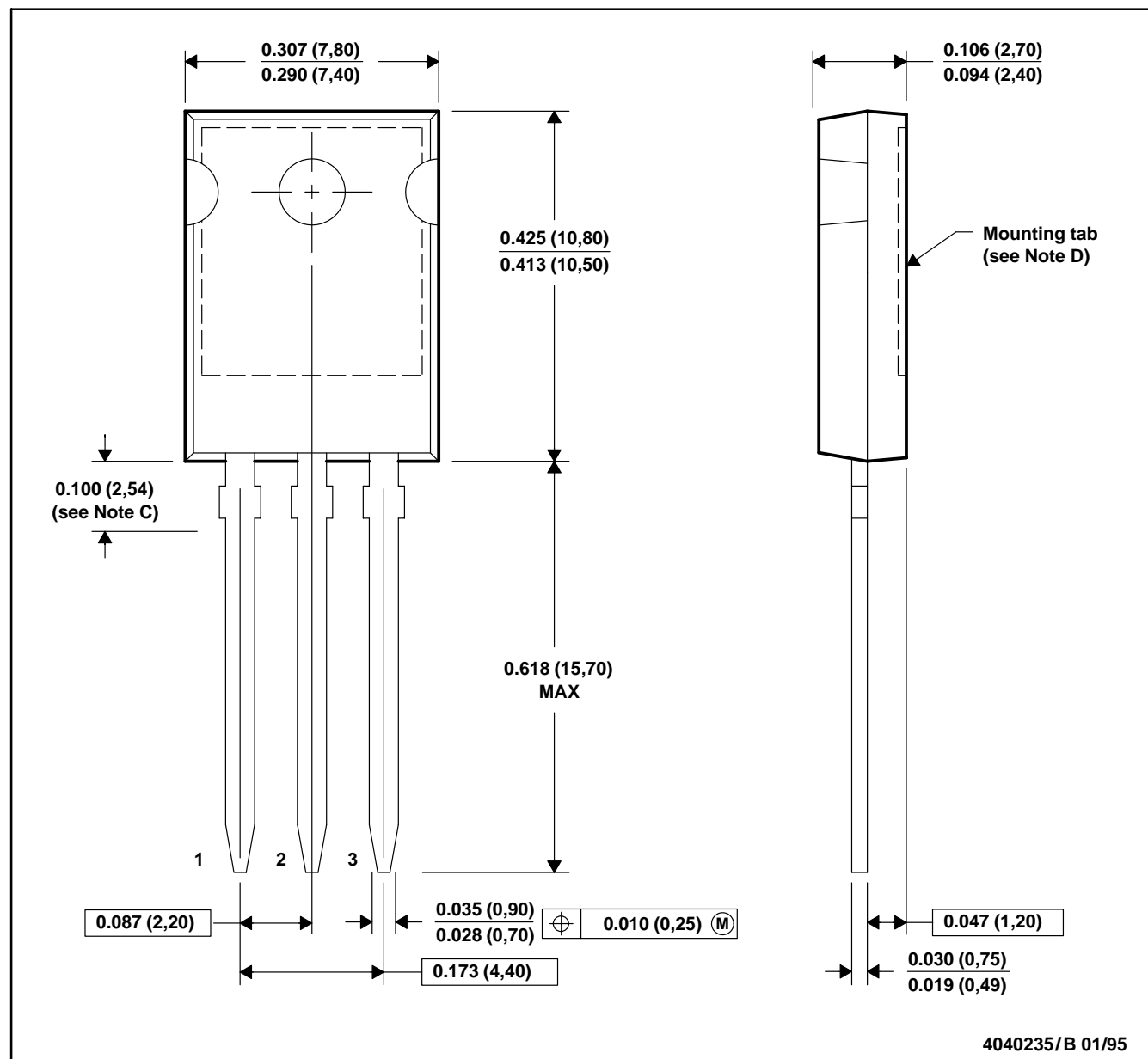


LL (R-PSFM-T3)

PLASTIC CLIP-MOUNT PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Lead dimensions are not controlled within this area.
 - The center lead is in electrical contact with the exposed mounting tab.
 - All lead dimensions apply before solder dip.

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